

Product Change Notification



- I. **Conversion to Lead-Free Plating (Step I)**
- II. **Reflow-Process Capable Components (Step II)**

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Dear Customer:

ITW and ITW divisions have always had a commitment to adhere to all applicable environmental regulations. There have been international initiatives to eliminate potentially hazardous materials from electrical and electronic products.

The European Union has initiated legislation: Directive 2002/95/EC of the European Parliament on the restriction of the use of certain hazardous substances in electrical and electronic equipment. This is also known as Restriction on Hazardous Substances (RoHS). This legislation requires that after July 1, 2006, newly marketed electrical and electronic equipment shall not contain any lead, mercury, cadmium, hexavalent chromium, polybromide biphenyl (PBB) or polybromide diphenyl ether (PBDE).

Products manufactured by ITW Pancon do not contain mercury, cadmium, hexavalent chromium, PBB's, or PBDE's. To satisfy customer requirements in the past, we have been using lead as an alloying element, in some product lines, in the tin-lead plating for connector contacts and pins. Our intent is to remove the lead as an alloying element. However, there may be trace levels of heavy metals remaining in the plating and plastic materials, which are not intentionally added, but are naturally occurring contaminants. These will be below the limits of 100 PPM for cadmium and 1000 PPM for lead in accordance with EoL directive (2000/53/EC).

Our customers have indicated to us that they also wish to comply with the international directives. We are assisting our customers in compliance by beginning to offer products that are lead-free and products that will work properly in the higher temperature lead-free soldering processes.

Our conversion process will occur in two steps:

1. The first step will be to convert existing Latcon[®] and Hicon[®] PCB product lines to a matte finish, lead-free, tin over nickel plating beginning in third quarter 2004 as a running change. That is, there will be no part number changes. Package labeling will indicate if the product is lead-free. There may be cases where lead-free and leaded products may appear together in shipments until existing inventories are used up.
2. The second step will be to offer the same product lines with new housings made from materials capable of withstanding the higher temperatures of lead-free reflow soldering. Select parts for lead free wave soldering may need to be revised as well. These new products will have new part numbers and be supplied with the matte finish, pure tin over nickel plating. These new parts may also include non-standard pin length variations to accommodate customers who use pin through paste processes.

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We have specified and tested new plastic materials for the bulk of our Latcon[®] and Hicon[®] PCB products and have sent out some samples for review and comment. These parts are lead-free process capable. We will be able to begin offering these products starting in fourth quarter of 2004.

Our Mascon[®] product line has always been lead-free with bright tin over nickel plating. Potential changes for this line are being reviewed with our customers and no specific timetable for changes is proposed at this time.

The changes to lead-free plating may require pricing changes but we will try to minimize the customer impact. The new part numbers for lead-free process capable parts will require modest price increases, at least initially.

In industries where exemptions are allowed, for customers who require tin-lead plating based on application needs, we will continue to offer tin-lead plating on a non-standard basis.

Customers should contact their Pancon Sales Representative or Pancon Customer Service person to discuss the availability and pricing for the part numbers they require.

For more information please contact:

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